

# Jun-Fa Mao

## List of Publications by Citations

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

226  
papers

2,552  
citations

25  
h-index

43  
g-index

360  
ext. papers

3,466  
ext. citations

2.8  
avg, IF

5.46  
L-index

#	Paper	IF	Citations
226	Circuit Modeling and Performance Analysis of Multi-Walled Carbon Nanotube Interconnects. <i>IEEE Transactions on Electron Devices</i> , <b>2008</b> , 55, 1328-1337	2.9	261
225	Harmonic suppression with photonic bandgap and defected ground structure for a microstrip patch antenna. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2005</b> , 15, 55-56	2.6	87
224	A New Balanced-to-Balanced Power Divider/Combiner. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2012</b> , 60, 2791-2798	4.1	86
223	Global interconnect width and spacing optimization for latency, bandwidth and power dissipation. <i>IEEE Transactions on Electron Devices</i> , <b>2005</b> , 52, 2272-2279	2.9	82
222	Design of a Beam Reconfigurable THz Antenna With Graphene-Based Switchable High-Impedance Surface. <i>IEEE Nanotechnology Magazine</i> , <b>2012</b> , 11, 836-842	2.6	79
221	Novel Substrate Integrated Waveguide Filters With Mixed Cross Coupling (MCC). <i>IEEE Microwave and Wireless Components Letters</i> , <b>2009</b> , 19, 701-703	2.6	78
220	An improved 1D periodic defected ground structure for microstrip line. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2004</b> , 14, 180-182	2.6	74
219	A Balanced-to-Balanced Power Divider With Arbitrary Power Division. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2013</b> , 61, 2831-2840	4.1	69
218	A Novel Single-Cavity Dual Mode Substrate Integrated Waveguide Filter With Non-Resonating Node. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2009</b> , 19, 368-370	2.6	65
217	A Four-Way Microstrip Filtering Power Divider With Frequency-Dependent Couplings. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2015</b> , 63, 3494-3504	4.1	62
216	Compact Lowpass Filters With Sharp and Expanded Stopband Using Stepped Impedance Hairpin Units. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2010</b> , 20, 310-312	2.6	56
215	A Half-Mode Substrate Integrated Waveguide Ring for Two-Way Power Division of Balanced Circuit. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2012</b> , 22, 333-335	2.6	53
214	An Overview of the Development of Antenna-in-Package Technology for Highly Integrated Wireless Devices. <i>Proceedings of the IEEE</i> , <b>2019</b> , 107, 2265-2280	14.3	49
213	A Systematic Electromagnetic-Circuit Method for EMI Analysis of Coupled Interconnects on Dispersive Dielectrics. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2013</b> , 61, 1-13	4.1	47
212	On-chip intercalated-graphene inductors for next-generation radio frequency electronics. <i>Nature Electronics</i> , <b>2018</b> , 1, 46-51	28.4	45
211	A Bandpass Graphene Frequency Selective Surface With Tunable Polarization Rotation for THz Applications. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2017</b> , 65, 662-672	4.9	44
210	Transient Analysis of CMOS-Gate-Driven $\text{\$RLGC\}$ Interconnects Based on FDTD. <i>IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems</i> , <b>2011</b> , 30, 574-583	2.5	43

209	A New Type of Periodically Loaded Half-Mode Substrate Integrated Waveguide and Its Applications. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2010</b> , 58, 882-893	4.1	42
208	. <i>IEEE Transactions on Advanced Packaging</i> , <b>2010</b> , 33, 729-737		29
207	Modeling and Fast Simulation of Multiwalled Carbon Nanotube Interconnects. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2015</b> , 57, 232-240	2	28
206	Accurate Characterization of Shielding Effectiveness of Metallic Enclosures With Thin Wires and Thin Slots. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2009</b> , 51, 293-300	2	27
205	Collaborative Design of a New Dual-Bandpass 180 <sup>°</sup> Hybrid Coupler. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2013</b> , 61, 1053-1066	4.1	26
204	Dualfunction Dielectric Resonator as Antenna and Phase-Delay-Line Load: Designs of Compact Circularly Polarized/Differential Antennas. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2018</b> , 66, 414-419	4.9	25
203	. <i>IEEE Transactions on Electron Devices</i> , <b>2011</b> , 58, 2689-2701	2.9	25
202	Shielding Characterization of Metallic Enclosures With Multiple Slots and a Thin-Wire Antenna Loaded: Multiple Oblique EMP Incidences With Arbitrary Polarizations. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2009</b> , 51, 284-292	2	25
201	Dynamic Power Model of CMOS Gates Driving Transmission Lines Based on Fourier Analysis. <i>IEEE Transactions on Electron Devices</i> , <b>2008</b> , 55, 594-600	2.9	25
200	A Precise Time-Step Integration Method for Transient Analysis of Lossy Nonuniform Transmission Lines. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2008</b> , 50, 166-174	2	25
199	Analyzing Large-Scale Non-Periodic Arrays With Synthetic Basis Functions. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2010</b> , 58, 3576-3584	4.9	24
198	Transient Electrothermal Analysis of Multilevel Interconnects in the Presence of ESD Pulses Using the Nonlinear Time-Domain Finite-Element Method. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2009</b> , 51, 774-783	2	24
197	Vertical Topologies of Miniature Multispiral Stacked Inductors. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2008</b> , 56, 475-486	4.1	22
196	. <i>IEEE Transactions on Advanced Packaging</i> , <b>2007</b> , 30, 851-863		22
195	Miniaturization of Rat-Race Coupler With Dual-Band Arbitrary Power Divisions Based on Stepped-Impedance Double-Sided Parallel-Strip Line. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2012</b> , 2, 2017-2030	1.7	21
194	Miniaturized Tapered EBG Structure With Wide Stopband and Flat Passband. <i>IEEE Antennas and Wireless Propagation Letters</i> , <b>2012</b> , 11, 314-317	3.8	21
193	Transient Thermal Analysis of GaN Heterojunction Transistors (HFETs) for High-Power Applications. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2007</b> , 17, 55-57	2.6	21
192	A Wideband Millimeter-Wave Substrate Integrated Coaxial Line Array for High-Speed Data Transmission. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2017</b> , 65, 2789-2800	4.1	20

191	Electrothermal Cosimulation of 3-D Carbon-Based Heterogeneous Interconnects. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2016</b> , 6, 518-526	1.7	19
190	Thermal Transient Response of GaAs FETs Under Intentional Electromagnetic Interference (EMI). <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2008</b> , 50, 340-346	2	18
189	Microstrip-Fed Differential Dielectric Resonator Antenna and Array. <i>IEEE Antennas and Wireless Propagation Letters</i> , <b>2018</b> , 17, 1736-1739	3.8	17
188	A Novel Compact Dual-Band Antenna Array With High Isolations Realized Using the Neutralization Technique. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2013</b> , 61, 1956-1962	4.9	17
187	Transient Thermal Analysis of 3-D Integrated Circuits Packages by the DGTD Method. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2017</b> , 7, 862-871	1.7	16
186	Quintuple-Mode W-Band Packaged Filter Based on a Modified Quarter-Mode Substrate-Integrated Waveguide Cavity. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2019</b> , 9, 2237-2247	1.7	15
185	A 0.5-1 GHz CMOS Low Noise Amplifier Using Dual-Channel Shunt Technique. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2010</b> , 20, 280-282	2.6	14
184	The enhancement of Q factor for patterned ground shield inductors at high temperatures. <i>IEEE Transactions on Magnetics</i> , <b>2006</b> , 42, 1873-1875	2	14
183	Design of a Novel Quarter-Mode Substrate-Integrated Waveguide Filter With Multiple Transmission Zeros and Higher ModeSuppressions. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2018</b> , 66, 5573-5584	4.1	14
182	Half-Mode Substrate Integrated Waveguide Dispersion Tailoring Using 2.5-D Spoof Surface Plasmon Polaritons Structure. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2020</b> , 68, 2539-2550	4.1	13
181	A Flat-Passband Microstrip Filter With Nonuniform- $Q$ Dual-Mode Resonators. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2016</b> , 26, 183-185	2.6	13
180	Overlapped optics induced perfect coherent effects. <i>Scientific Reports</i> , <b>2013</b> , 3, 3569	4.9	13
179	Transient analysis of lossy interconnects by modified method of characteristics. <i>IEEE Transactions on Circuits and Systems Part 1: Regular Papers</i> , <b>2000</b> , 47, 363-375		13
178	Time-Domain Investigation on Cable-Induced Transient Coupling Into Metallic Enclosures. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2009</b> , 51, 953-962	2	12
177	Three-pole cross-coupled substrate-integrated waveguide bandpass filters based on PCB process and multilayer LTCC technology. <i>Microwave and Optical Technology Letters</i> , <b>2009</b> , 51, 71-73	1.2	12
176	Substrate Integrated Waveguide Filter With Flat Passband Based on Complex Couplings. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2018</b> , 28, 494-496	2.6	11
175	Wideband Pulse Responses of Metallic Rectangular Multistage Cascaded Enclosures Illuminated by an EMP. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2008</b> , 50, 928-939	2	11
174	A Single-Ended-to-Balanced Impedance-Transforming Branch-Line Coupler With Arbitrary Power Division Ratio. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2019</b> , 67, 949-956	4.1	10

173	A Balanced-to-Balanced Rat-Race Coupling Network Based on Defected Slots. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2019</b> , 29, 459-461	2.6	10
172	Immunity Analysis and Experimental Investigation of a Low-Noise Amplifier Using a Transient Voltage Suppressor Diode Under Direct Current Injection of HPM Pulses. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2014</b> , 56, 1715-1718	2	10
171	Embedded Planar EBG and Shorting Via Arrays for SSN Suppression in Multilayer PCBs. <i>IEEE Antennas and Wireless Propagation Letters</i> , <b>2012</b> , 11, 1430-1433	3.8	10
170	Average power handling capability of finite-ground thin-film microstrip lines over ultra-wide frequency ranges. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2005</b> , 15, 715-717	2.6	10
169	A new compact 1D PBG microstrip structure with wider stopband based on semiconductor substrate. <i>Microwave and Optical Technology Letters</i> , <b>2003</b> , 39, 150-152	1.2	10
168	Integrated multi-scheme digital modulations of spoof surface plasmon polaritons. <i>Science China Information Sciences</i> , <b>2020</b> , 63, 1	3.4	10
167	Large Displacement Motion Interferometry With Modified Differentiate and Cross-Multiply Technique. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2021</b> , 1-1	4.1	10
166	Low-Profile Broadband Plasma Antenna for Naval Communications in VHF and UHF Bands. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2020</b> , 68, 4271-4282	4.9	9
165	Equivalent Surface Impedance-Based Mixed Potential Integral Equation Accelerated by Optimized $\mathcal{H}$ -Matrix for 3-D Interconnects. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2018</b> , 66, 22-34	4.1	9
164	A Compact Single/Dual-Polarized Broadband Antenna With SUM and Difference Beam Capabilities. <i>IEEE Antennas and Wireless Propagation Letters</i> , <b>2010</b> , 9, 990-993	3.8	9
163	Mushroom-Type Ground Plane Structure for Wideband SSN Suppression in High-Speed Circuits. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2011</b> , 21, 646-648	2.6	9
162	Noncontact High-Linear Motion Sensing Based on A Modified Differentiate and Cross-Multiply Algorithm <b>2020</b> ,		8
161	Heatsink Antenna Array for Millimeter-Wave Applications. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2020</b> , 68, 7664-7669	4.9	8
160	Compact Tunable Bandpass Filter With a Fixed Out-of-Band Rejection Based on Hilbert Fractals. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2013</b> , 3, 391-400	1.7	8
159	A wide band millimeter-wave substrate integrated coaxial line (SICL) for high speed data transmission <b>2015</b> ,		8
158	A new floating active inductor using resistive Feedback Technique <b>2010</b> ,		8
157	Parameters extraction and modeling for planar spiral inductor on Si-SiO <sub>2</sub> /substrates by DDM for conformal modules. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2003</b> , 51, 1763-1766	4.1	8
156	A novel photonic band-gap microstrip structures for low-pass filters of wide stop-band. <i>Microwave and Optical Technology Letters</i> , <b>2003</b> , 37, 470-472	1.2	8

155	A Wideband Filtering Balanced-to-Unbalanced Out-of-Phase Power Divider. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2018</b> , 28, 870-872	2.6	8
154	Novel Surface Impedance Modeling for Broadband Parameter Extraction of 3-D Interconnects. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2017</b> , 27, 7-9	2.6	7
153	Transient Electromagnetic-Thermal Simulation of Dispersive Media Using DGTD Method. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2019</b> , 1-9	2	7
152	Cavity Model Analysis of a Dual-Probe-Feed Circular Microstrip Patch Antenna. <i>IEEE Antennas and Wireless Propagation Letters</i> , <b>2016</b> , 15, 44-47	3.8	6
151	An Electrically Steerable Parasitic Array Radiator in Package Based on Liquid Crystal. <i>IEEE Antennas and Wireless Propagation Letters</i> , <b>2019</b> , 18, 2365-2369	3.8	6
150	Analysis on a 77 GHz MIMO Radar for Touchless Gesture Sensing <b>2020</b> , 1-1		6
149	A Novel Automatically Designed EBG Structure by Improved GA for Ultrawideband SSN Mitigation of System in Package. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2020</b> , 10, 123-133	1.7	6
148	Stacked patch array in LTCC for 28 GHz antenna-in-package applications <b>2017</b> ,		6
147	Compact quasi-elliptic bandpass filter based on folded ridge substrate integrated waveguide (FRSIW) <b>2012</b> ,		6
146	Implementation of New CMOS Differential Stacked Spiral Inductor for VCO Design. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2007</b> , 17, 727-729	2.6	6
145	Characteristic analysis of coupled HTS interconnects with two-dimensional FDTD. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2001</b> , 11, 33-35	2.6	6
144	A New Compact Power Divider Based on Capacitor Central Loaded Coupled Microstrip Line. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2020</b> , 68, 4249-4256	4.1	6
143	An Overview of Probe-Based Millimeter-Wave/Terahertz Far-Field Antenna Measurement Setups [Measurements Corner]. <i>IEEE Antennas and Propagation Magazine</i> , <b>2021</b> , 63, 63-118	1.7	6
142	A Slow Wave Ridged Half-Mode Substrate Integrated Waveguide With Spoof Surface Plasmon Polaritons. <i>IEEE Transactions on Plasma Science</i> , <b>2021</b> , 49, 1818-1825	1.3	6
141	A Wideband Differentially Fed Dual-Polarized Laminated Resonator Antenna. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2021</b> , 69, 4148-4153	4.9	6
140	. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2020</b> , 10, 1367-1374	1.7	5
139	Efficient Transient Thermal Simulation of ICs and Packages With Laguerre-Based Finite-Element Method. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2020</b> , 10, 203-211	1.7	5
138	A Generalized Transition Matrix Model for Open-Ended Cavity With Complex Internal Structures. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2016</b> , 64, 3920-3930	4.9	5

137	Experiments and Comparisons of Power to Failure for SiGe-Based Low-Noise Amplifiers Under High-Power Microwave Pulses. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2018</b> , 60, 1427-1435	2	5
136	Fast Nested Cross Approximation Algorithm for Solving Large-Scale Electromagnetic Problems. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2019</b> , 67, 3271-3283	4.1	5
135	A new quad-band Wilkinson power divider. <i>Journal of Electromagnetic Waves and Applications</i> , <b>2014</b> , 28, 1622-1634	1.3	5
134	A Note on the Construction of Synthetic Basis Functions for Antenna Arrays. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2012</b> , 60, 3509-3512	4.9	5
133	N+1 transmission zeros in Nth-order cross-coupled filter with mixed source and load coupling (MSLC) <b>2009</b> ,		5
132	Design of multilayer triangular substrate integrated waveguide filter in LTCC. <i>Microwave and Optical Technology Letters</i> , <b>2009</b> , 51, 2582-2585	1.2	5
131	Numerical Dispersion Characteristics of the Three-dimensional Precise Integration Time-Domain Method. <i>IEEE MTT-S International Microwave Symposium Digest IEEE MTT-S International Microwave Symposium</i> , <b>2007</b> ,		5
130	Analysis of interconnects with frequency-dependent parameters by differential quadrature method. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2005</b> , 15, 877-879	2.6	5
129	A PEEC with a new capacitance model for circuit simulation of interconnects and packaging structures. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2000</b> , 48, 281-287	4.1	5
128	Accurate Measurement of Human Vital Signs with Linear FMCW Radars under Proximity Stationary Clutters. <i>IEEE Transactions on Biomedical Circuits and Systems</i> , <b>2021</b> , PP,	5.1	5
127	Fast Analytic Electromigration Analysis for General Multisegment Interconnect Wires. <i>IEEE Transactions on Very Large Scale Integration (VLSI) Systems</i> , <b>2020</b> , 28, 421-432	2.6	5
126	Multibranch Rao-Wilton-Ilissoon Basis Functions for Electromagnetic Scattering Problems. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2021</b> , 1-1	4.9	5
125	Compact Fractional-Order Model of On-Chip Inductors With BCB on High Resistivity Silicon. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2020</b> , 10, 878-886	1.7	4
124	Hybrid cross approximation for electric field integral equation based scattering analysis <b>2017</b> ,		4
123	High-Frequency Electrothermal Characterization of TSV-Based Power Delivery Network. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2018</b> , 8, 2171-2179	1.7	4
122	Signal-Integrity Optimization for Complicated Multiple-Input Multiple-Output Networks Based on Data Mining of S-Parameters. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2014</b> , 4, 1184-1192	1.7	4
121	Analysis and Optimization of Thermal-Driven Global Interconnects in Nanometer Design. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2011</b> , 1, 1564-1572	1.7	4
120	Design a PIFA with fold-type ground plane for dual frequency mobile phone. <i>Microwave and Optical Technology Letters</i> , <b>2008</b> , 50, 2258-2262	1.2	4

119	Time-domain modeling of high-speed interconnects by modified method of characteristics. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2000</b> , 48, 323-327	4.1	4
118	An Ultrawideband Magnetic Probe With High Electric Field Suppression Ratio. <i>IEEE Transactions on Instrumentation and Measurement</i> , <b>2021</b> , 70, 1-9	5.2	4
117	Diagnosis and tuning of filtering antenna based on extracted coupling matrix <b>2016</b> ,		4
116	A Flat Passband Predistorted Bandpass Filter with Folded Substrate Integrated Waveguide. <i>IEEE Transactions on Circuits and Systems II: Express Briefs</i> , <b>2021</b> , 1-1	3.5	4
115	Miniaturization of Frequency-Reconfigurable Antenna Using Periodic Slow-Wave Structure. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2021</b> , 1-1	4.9	4
114	Dual-sleeve wideband monopole antenna for shipborne systems in VHF band. <i>Electronics Letters</i> , <b>2018</b> , 54, 1102-1104	1.1	4
113	An Analytical Gradient Model for the Characterization of Conductor Surface Roughness Effects <b>2018</b> ,		4
112	Low-Loss Heterogeneous Integrations With High Output Power Radar Applications at W-Band. <i>IEEE Journal of Solid-State Circuits</i> , <b>2021</b> , 1-1	5.5	4
111	Active Integrated Dielectric Resonator Antenna-in-Package Design. <i>IEEE Antennas and Wireless Propagation Letters</i> , <b>2019</b> , 18, 2414-2418	3.8	3
110	Integration of $\text{SS}\text{\$}$ /Ka/ $\text{\$D}\text{\$}$ -Band Antennas in LTCC With a Cylindrical Radome for Triband Applications. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2019</b> , 67, 5781-5789	4.9	3
109	Ruggedness Characterization of Bonding Wire Arrays in LD MOSFET-Based Power Amplifiers. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2018</b> , 8, 1032-1041	1.7	3
108	High-Speed Interconnect System Using QPSK Scheme Based on Substrate Integrated Waveguide. <i>Journal of Circuits, Systems and Computers</i> , <b>2018</b> , 27, 1850014	0.9	3
107	Modified FSIW Filter With $\text{\$N}\text{\$}$ Transmission Zeros Using BCB-Based MEMS Technology. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2019</b> , 29, 520-522	2.6	3
106	A Pair of Parallel Differential Magnetic-Field Probes with High Spatial Resolution and Wide Frequency Bandwidth <b>2019</b> ,		3
105	New Power Distribution Network Design Method for Digital Systems Using Time-Domain Transient Impedance. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2013</b> , 3, 1399-1408	1.7	3
104	<b>2014</b> ,		3
103	High-speed data transmission system using half mode substrate integrated waveguide <b>2014</b> ,		3
102	Investigation on dual-armed sinuous antenna <b>2012</b> ,		3



101	Finite-Difference Analysis of Interconnects With Frequency-Dependent Parameters Based on Equivalent Circuit Models. <i>IEEE Transactions on Advanced Packaging</i> , <b>2010</b> , 33, 457-467		3
100	A New Systematic Method for the Modeling, Analysis, and Design of High-Speed Power-Delivery Networks by Using Distributed Port. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2010</b> , 58, 2940-2951	4.1	3
99	Design of a switchable high impedance surface based on single-layer doped graphene for THz application <b>2011</b> ,		3
98	Study on equivalent single conductor model of multi-walled carbon nanotube interconnects <b>2012</b> ,		3
97	Microstrip patch antenna array on ground with circular PBG. <i>Microwave and Optical Technology Letters</i> , <b>2004</b> , 41, 127-130	1.2	3
96	Deep Sub-Wavelength Millimeter-Wave Radar Interferometry with a Novel Ego-Motion based Calibration Technique <b>2021</b> ,		3
95	Miniaturized Half-Mode T-Septum SIW Bandpass Filter With an Ultrawide Stopband. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2021</b> , 31, 853-856	2.6	3
94	A Compact 2-D WLP-FDTD Method for Superconducting Microstrip Lines <b>2018</b> ,		3
93	High Modes Suppressions with Transmission Zeros Design for a Novel Quarter-mode SIW Filter <b>2018</b> ,		3
92	4-D Gesture Sensing Using Reconfigurable Virtual Array Based on a 60-GHz FMCW MIMO Radar Sensor. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2022</b> , 1-1	4.1	3
91	Time-Domain Analysis of Noise Coupling Between Package and PCB Power/Ground Planes Based on WLP-FDTD. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2017</b> , 7, 269-275	1.75	2
90	High-Frequency Analysis of Intercalated Multilayer Graphene (IMLG) and Implication for Tunable Terahertz Resonator Design. <i>IEEE Access</i> , <b>2017</b> , 5, 7532-7541	3.5	2
89	A General Method for Balanced-to-Unbalanced Filtering Out-of-Phase Power Divider Design. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2019</b> , 67, 2693-2700	4.1	2
88	A Novel Design of Compact Out-of-Phase Power Divider With Arbitrary Ratio. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2020</b> , 68, 5235-5243	4.1	2
87	Mixed-Mode Property of Defected Ground Structure and Its Application in Balanced Network Design With Harmonic Suppression. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2018</b> , 28, 188-190	2.6	2
86	Fast transient electro-thermal simulation of on-chip interconnects in the presence of ESD pulses <b>2015</b> ,		2
85	Notched ultra-wideband (UWB) bandpass filter with wide upper stopband based on electromagnetic bandgap (EBG) structures <b>2012</b> ,		2
84	A New Power-Ground Plane Modeling Method With Rectangle and Triangle Segmentation. <i>IEEE Transactions on Advanced Packaging</i> , <b>2010</b> , 33, 639-646		2

83	Study on multi-walled carbon nanotube resonator <b>2010</b> ,		2
82	Thermal runaway prediction based on electrothermal models in nanotechnologies <b>2011</b> ,		2
81	Equivalence Principle for Analyzing Steady-State Heat Conduction Problems. <i>Numerical Heat Transfer, Part B: Fundamentals</i> , <b>2011</b> , 59, 226-244	1.3	2
80	Experimental demonstration of the wave squeezing effect based on inductor-capacitor networks. <i>Applied Physics Letters</i> , <b>2012</b> , 101, 074104	3.4	2
79	A meandering dual-mode bandpass filter with rectangular-loop perturbation. <i>Microwave and Optical Technology Letters</i> , <b>2010</b> , 52, 2356-2359	1.2	2
78	Design of Minimized Electromagnetic Bandgap Structure High Temperature Superconducting Filter <b>2008</b> ,		2
77	Analytical delay models for RLC interconnects under ramp input. <i>Frontiers of Electrical and Electronic Engineering in China: Selected Publications From Chinese Universities</i> , <b>2007</b> , 2, 88-91		2
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75	Performance degradation of some on-chip finite-ground coplanar waveguide (FGCPW)-built passive devices at high temperature. <i>Microwave and Optical Technology Letters</i> , <b>2006</b> , 48, 1754-1759	1.2	2
74	Modeling of carbon nanotube interconnects and comparative analysis with Cu interconnects <b>2006</b> ,		2
73	Parameter extraction for on-chip interconnects by double-image Green's function method combined with hierarchical algorithm. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2005</b> , 53, 2416-2423	4.1	2
72	A Portable 5.8 GHz Dual Circularly Polarized Interferometric Radar Sensor for Short-Range Motion Sensing. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2022</b> , 1-1	4.9	2
71	Mitigation of Leakage and Stationary Clutters in Short-Range FMCW Radar With Hybrid Analog and Digital Compensation Technique. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2022</b> , 70, 62-73 <sup>4.1</sup>	4.1	2
70	Loop-Star Functions Including Multibranch Raw-Wilton-Glisson Basis Functions. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2021</b> , 1-1	4.9	2
69	DC IR-Drop Analysis of Power Distribution Networks by a Robin Transmission Condition Enhanced Discontinuous Galerkin Method. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2021</b> , 1-1	1.7	2
68	Ridged Substrate Integrated Coaxial Line for Wideband Millimeter-Wave Transmission. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2021</b> , 69, 2981-2988	4.1	2
67	A 24 GHz Microstrip Comb Array Antenna With High Sidelobe Suppression for Radar Sensor. <i>IEEE Antennas and Wireless Propagation Letters</i> , <b>2021</b> , 20, 1220-1224	3.8	2
66	A SIW-fed Parasitic Cavity Resonator Antenna in LTCC Technology <b>2019</b> ,		2

65	A Semianalytical Gradient Model for Characterization of Conductors With Surface Roughness. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2018</b> , 66, 5391-5398	4.1	2
64	Theoretical and Experimental Investigation of HMSIW-Based High-Speed Data Transmission System Using QPSK Scheme. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2018</b> , 8, 1938-1947	1.7	2
63	Pattern-Steerable Endfire Plasma Array Antenna. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2021</b> , 1-1	4.9	2
62	A Wideband Microstrip-Fed Dielectric Resonator Antenna Array With Defected Ground Structure <b>2019</b> ,		1
61	FLAT-PASSBAND SUBSTRATE INTEGRATED WAVEGUIDE FILTER WITH RESISTIVE COUPLINGS. <i>Progress in Electromagnetics Research C</i> , <b>2016</b> , 62, 1-10	0.9	1
60	Lossy substrate integrated waveguide filter with flat passband <b>2016</b> ,		1
59	Electromagnetic-thermal simulation of Lorentz media by the DGTD method <b>2018</b> ,		1
58	Worst Case Power Noise Estimation and Compensation Design for Zero Coupling with Multiple Switching I/Os. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2012</b> , 54, 1105-1111	2	1
57	An efficient intra-frame rate control algorithm for H.264/AVC video coding. <i>Wuhan University Journal of Natural Sciences</i> , <b>2012</b> , 17, 243-248	0.4	1
56	Performance enhancement research for printed circuit board manufacture in China <b>2011</b> ,		1
55	A bandstop filter based on non-bianisotropic complementary split ring resonators (NBCSRRs) <b>2011</b> ,		1
54	Configurable secure ECC hardware module for resource constrained device <b>2009</b> ,		1
53	Transient thermal analysis of global interconnects based on transmission lines <b>2012</b> ,		1
52	Electrothermal coupling analysis of CMOS gates driving interconnects <b>2012</b> ,		1
51	Analysis of frequency-dependent lossy transmission lines driven by CMOS gates <b>2009</b> ,		1
50	An area-efficient very large scale integration architecture for modified Euclidean algorithm with dynamic storage technique. <i>International Journal of Electronics</i> , <b>2009</b> , 96, 837-842	1.2	1
49	A differential quadrature method for the transient analysis of multiconductor transmission lines <b>2008</b> ,		1
48	Global Interconnect Analysis and Optimization for Nanometer Scale VLSI <b>2006</b> ,		1

47	Numerical investigation on thermal characteristics of GaN HFETs for high power applications <b>2006</b> ,		1
46	Shielding Effectiveness Characterization of Metallic Rectangular Cascaded Enclosures <b>2007</b> ,		1
45	Optimization of global interconnects in high performance VLSI circuits <b>2006</b> ,		1
44	The inductance model of coupled high-Tc superconducting microstrip lines. <i>IEEE Transactions on Applied Superconductivity</i> , <b>2004</b> , 14, 7-12	1.8	1
43	Phase Correction in Asynchronous FMCW Radar Systems for Accurate Noncontact Cardiopulmonary Monitoring <b>2021</b> ,		1
42	A 4D Gesture Sensing Technique based on Spatiotemporal Detection with a 60 GHz FMCW MIMO Radar <b>2021</b> ,		1
41	Millimeter-Wave Active Integrated Semielliptic CPW Slot Antenna With Ultrawideband Compensation of Ball Grid Array Interconnection. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2021</b> , 1-1	1.7	1
40	Microstrip Memristive Switch and Its Applications to RF Devices <b>2020</b> ,		1
39	Memristive Switch for Intelligent RF Applications <b>2020</b> ,		1
38	An Optimal Approach in Design of Microstrip-to- SIW Transition Using Bayesian Optimization <b>2020</b> ,		1
37	A Compact 2-D Stochastic FDTD Method for Uncertainty Analysis in Superconducting Transmission Lines. <i>IEEE Transactions on Applied Superconductivity</i> , <b>2020</b> , 30, 1-7	1.8	1
36	Design of Substrate Integrated Coaxial Line under Silicon-based MEMS Process <b>2019</b> ,		1
35	A Fast Semi-Analytic Approach for Combined Electromigration and Thermomigration Analysis for General Multisegment Interconnects. <i>IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems</i> , <b>2021</b> , 40, 350-363	2.5	1
34	Vivaldi Antenna Array with Heat Dissipation Enhancement for Millimeter-Wave Applications. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2021</b> , 1-1	4.9	1
33	Transient Electro-Thermal Analysis of On-Chip Interconnects in the Presence of ESD Pulses Using DGTD Method <b>2018</b> ,		1
32	Wafer level heterogeneous integration of a millimeter-wave transceiver module and its EMC problems <b>2018</b> ,		1
31	. <i>IEEE Transactions on Antennas and Propagation</i> , <b>2021</b> , 69, 4681-4687	4.9	1
30	PhysioChair: A Dual-Frequency Radar System for Noninvasive and Continuous Detection of Physiological Signatures. <i>IEEE Sensors Journal</i> , <b>2022</b> , 1-1	4	1

29	Analytical Thermal Model for AlGa <sub>N</sub> /Ga <sub>N</sub> HEMTs Using Conformal Mapping Method. <i>IEEE Transactions on Electron Devices</i> , <b>2022</b> , 1-6	2.9	1
28	Contactless Measurement of Human Systolic Time Intervals Based on Doppler Cardiograms in Clinical Environment. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2022</b> , 1-4	2.6	1
27	Theoretical and Experimental Investigations on Differential Aperture-Coupled Rectangular Laminated Resonator Antenna. <i>IEEE Antennas and Wireless Propagation Letters</i> , <b>2022</b> , 1-1	3.8	1
26	DC-Independent High-Linear Motion Sensing Based on a Novel ACAA Algorithm. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2022</b> , 32, 261-264	2.6	1
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24	Interferometric Motion Sensing With a Single-Channel Radar Sensor Based on a Novel Calibration-Free Phase Demodulation Technique. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2022</b> , 1-4	2.6	1
23	Modeling of power-plane segmentation with cavity and planar-lumped models <b>2010</b> ,		0
22	Design of Compact Grid Array Antennas Using Gradient Slow-Wave Structures. <i>IEEE Antennas and Wireless Propagation Letters</i> , <b>2022</b> , 1-1	3.8	0
21	An Unconditionally Stable 2-D Stochastic WLP-FDTD Method for Geometric Uncertainty in Superconducting Transmission Lines. <i>IEEE Transactions on Applied Superconductivity</i> , <b>2022</b> , 32, 1-9	1.8	0
20	Efficient transient thermal simulation with Laguerre-based finite-element method and domain decomposition. <i>Numerical Heat Transfer, Part B: Fundamentals</i> , <b>2021</b> , 80, 14-28	1.3	0
19	Transient Coanalysis of Multicoupled Passive Transmission Lines and Josephson Junctions Based on FDTD. <i>IEEE Transactions on Applied Superconductivity</i> , <b>2020</b> , 30, 1-7	1.8	0
18	A New Gysel Out-of-Phase Power Divider With Arbitrary Power Dividing Ratio Based on Analysis Method of Equivalence of N-Port Networks. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2021</b> , 69, 1335-1343	4.1	0
17	Nonlinear Thermal Analysis of AlGa <sub>N</sub> /Ga <sub>N</sub> HEMTs With Temperature-Dependent Parameters. <i>IEEE Transactions on Electron Devices</i> , <b>2021</b> , 68, 4565-4570	2.9	0
16	$\mathcal{H}$ -Matrix Accelerated Contour Integral Method for Modeling Multiconductor Transmission Lines. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2018</b> , 60, 552-555	2	
15	Analyzing Electromagnetic Systems on Electrically Large Platform Using a GTM-PO Hybrid Method with Synthetic Basis Functions. <i>International Journal of Antennas and Propagation</i> , <b>2014</b> , 2014, 1-7	1.2	
14	An efficient CMOS on-chip ladder reflector antenna for inter-chip communications. <i>Microwave and Optical Technology Letters</i> , <b>2009</b> , 51, 59-63	1.2	
13	Multi-dimensional asymptotic waveform evaluation method and adaptive hopping technique. <i>International Journal of RF and Microwave Computer-Aided Engineering</i> , <b>2008</b> , 18, 233-241	1.5	
12	Improved circuit model for coplanar-waveguide to microstrip-line transition on silicon substrate. <i>Microwave and Optical Technology Letters</i> , <b>2008</b> , 50, 141-144	1.2	

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10	IFDR: An Efficient Iterative Optimization Algorithm for Standard Cell Placement. <i>Active and Passive Electronic Components</i> , <b>2004</b> , 27, 189-195	0.3
9	A novel direct parameter-extraction method for GaInP/GaAs HBTs small-signal model. <i>International Journal of RF and Microwave Computer-Aided Engineering</i> , <b>2004</b> , 14, 447-452	1.5
8	Conductive Bridging-Based Memristive RF Switches on a Silicon Substrate. <i>IEEE Transactions on Microwave Theory and Techniques</i> , <b>2022</b> , 70, 24-34	4.1
7	An Unequal Wilkinson Power Divider Based on Integrated Passive Device Technology and Parametric Model. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2021</b> , 1-4	2.6
6	A novel numerical method for steady-state thermal simulation based on loop-tree and HBRWG basis functions. <i>Numerical Heat Transfer, Part B: Fundamentals</i> , <b>2020</b> , 78, 348-363	1.3
5	A quantification control method of electromagnetic environmental effects for complex systems. <i>Journal of Electromagnetic Waves and Applications</i> , <b>2021</b> , 35, 245-261	1.3
4	Protection Effects Using Transient Voltage Suppressor Diodes Based Circuits Under High-Power Microwave Pulses. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2021</b> , 1-7	2
3	Average Power Handling Capability of Microstrip Lines Considering Heat Convection and Self-Heating Effects with Temperature-Dependent Resistivity. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2022</b> , 1-1	1.7
2	Two-Material-Filled Ridge Half-Mode Substrate Integrated Waveguide for Monomode Bandwidth Enhancement. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2022</b> , 1-4	2.6
1	A High-Isolation Duplexer With Mismatched Load Impedance for Integrated Sensing and Communication. <i>IEEE Microwave and Wireless Components Letters</i> , <b>2022</b> , 1-4	2.6